## **ASMT-CB00**

InGaN Blue, 0.4mm Low Profile Right Angle Surface Mount ChipLED



# **Data Sheet**

### Description

The ASMT-CB00 of blue color chip-type LEDs is designed with the smallest footprint to achieve high density of components on board. They have the industry standard footprint 1.6 mm x 1.0 mm and a height of only 0.4 mm. This makes them very suitable for cellular phone and mobile equipment backlighting and indication application where space is a constraint. In order to facilitate automated pick and place operation, these ChipLEDs are shipped in conductive tape and reel, with 4000 units per reel. These part are compatible with IR soldering.

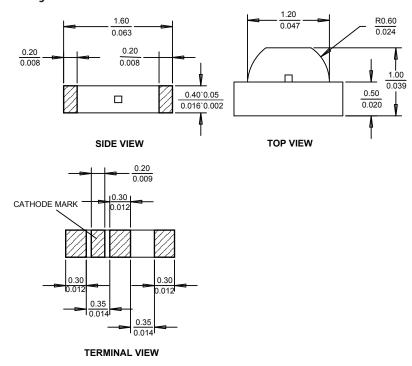
### **Features**

- Small size right angle mount
- 0603 industry standard footprint
- 0.4 mm low profile type
- Operating temperature range of -30°C to +85 °C
- Compatible with IR reflow soldering process
- Available in 8mm tape on 178mm (7') diameter reels
- Reel sealed in zip locked moisture barrier bags

### **Applications**

- LCD Backlighting
- Keypad Side / Backlighting
- Pushbutton backlighting
- Symbol Indicator

### **Package Dimension**



#### Notes:

- 1. All dimensions will be in millimeters (inches)
- 2. Tolerance is  $\pm 0.1 mm$  ( $\pm 0.004$  in) unless otherwise stated

**CAUTION:** ASMT-CB00 LEDs are Class 1A ESD sensitive per JESD22-A114C.01. Please observe appropriate precautions during handling and processing. Refer to Application Note AN-1142 for additional details.

### **Device Selection Guide**

Package Dimension (mm)	Parts per Reel	Package Description
1.6 (L) x 1.0 (W) x 0.4 (H)	4000	Untinted, Non-diffused

# Absolute Maximum Ratings at $T_A = 25^{\circ}C$

Parameter	ASMT-CB00	Unit
DC Forward Current [1]	10	mA
Power Dissipation	32	mW
Reverse Voltage (I <sub>R</sub> = 100μA)	5	V
LED Junction Temperature	95	°C
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range	-40 to +85	°C
Soldering Temperature	See reflow soldering profile (Figure 7 & 8)	

Note:

# Electrical Characteristics at $T_A = 25^{\circ}C$

	Forward Volt V <sub>F</sub> (Volts) <sup>[1]</sup>		Reverse Breakdown V <sub>R</sub> (Volts) @ I <sub>R</sub> = 100μA	Thermal Resistance R <sub>HJ-PIN</sub> (°C/W)	
Part Number	Тур.	Max.	Min.	Тур.	
ASMT-CB00	2.85	3.15	5	450	

Notes:

# Optical Characteristics at $T_A = 25^{\circ}C$

	Luminous I Iv <sup>[1]</sup> (mcd)	•	Peak Wavelength $\lambda_{ m peak}$ (nm)	Dominant Wavelength $\lambda_{\mathbf{d}}^{[2]}$ (nm)	Viewing Angle 2 θ <sub>1/2</sub> <sup>[3]</sup> (Degrees)
Part Number	Min.	Тур.	Тур.	Тур.	Тур.
ASMT-CB00	7.2	18	469	473	150

Notes

<sup>1.</sup> Derate linearly as shown in Figure 4.

<sup>1.</sup> Vf tolerance: ±0.1V

<sup>1.</sup> The luminous intensity I<sub>V</sub> is measured at the peak of the spatial radiation pattern which may not be aligned with the mechanical axis of the LED package.

<sup>2.</sup> The dominant wavelength,  $\lambda_d$ , is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.

<sup>3.</sup>  $\theta_{1/2}$  is the off-axis angle where the luminous intensity is ½ the peak intensity.

## Light Intensity (I<sub>V</sub>) Bin Limits

	Intensity (mcd)		
Bin ID	Minimum	Maximum	
K	7.20	11.20	
L	11.20	18.00	
M	18.00	28.50	

Tolerance: ±15%

Notes:

### **Color Bin Limits**

	Dominant Wavel	Dominant Wavelength (nm)		
Bin ID	Minimum	Maximum		
A	460.0	465.0		
В	465.0	470.0		
C	470.0	475.0		
D	475.0	480.0		

 $Tolerance: \pm 1 nm$ 

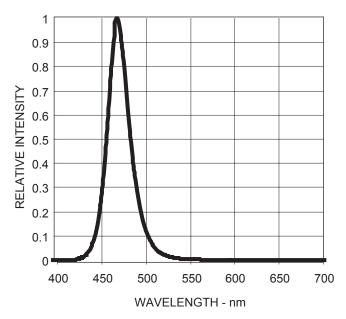


Figure 1. Relative intensity vs. wavelength

## Forward Voltage (V<sub>F</sub>) Bin Limits

	Forward Voltage	e (V)
Bin ID	Minimum	Maximum
1	2.55	2.75
2	2.75	2.95
3	2.95	3.15

Tolerance: ±0.1V

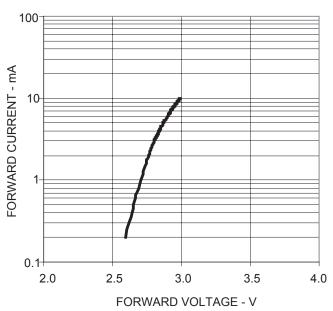


Figure 2. Forward current vs. forward voltage

Bin categories are established for classification of products. Products may not be available in all categories. Please contact your Avago representative for information on current available bins.

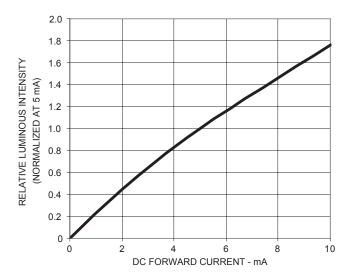


Figure 3. Luminous intensity vs. forward current

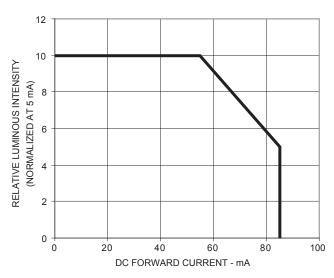


Figure 4. Maximum forward current vs. ambient temperature

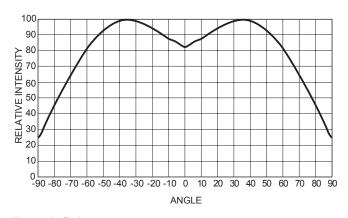
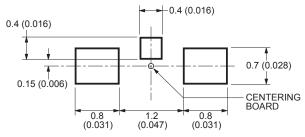


Figure 5. Radiation pattern



### Notes:

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Figure 6. Recommended soldering land pattern

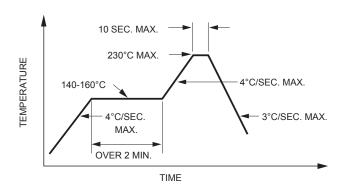


Figure 7. Recommended reflow soldering profile

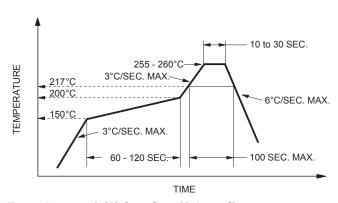


Figure 8. Recommended Pb-free reflow soldering profile

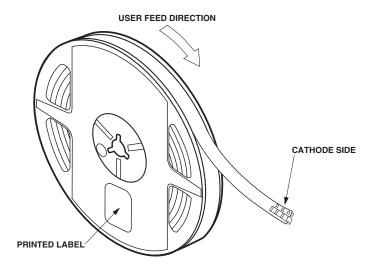


Figure 9. Reeling orientation

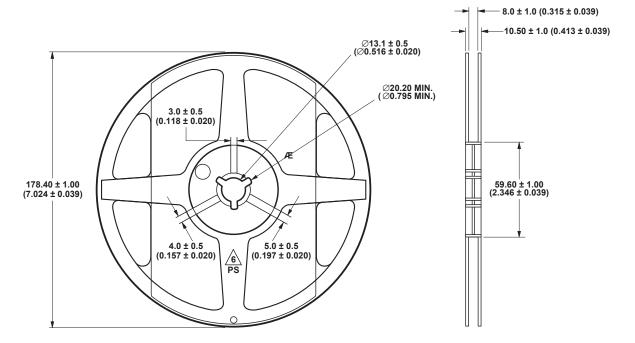
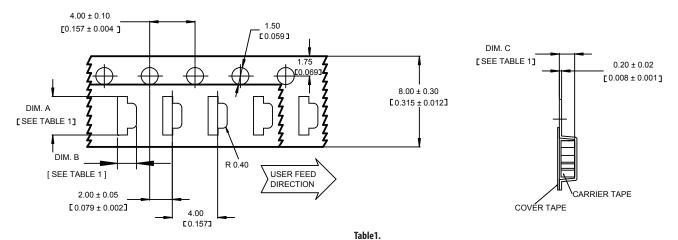


Figure 10. Reel dimensions

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 PART NUMBER
 DIM.A ± 0.10 (0.004)
 DIM.B ± 0.10 (0.004)
 DIM.C ± 0.10 (0.004)

 ASMT-CA00
 1.75 (0.069)
 1.10 (0.043)
 0.60 (0.024)

Dimensions In Millimeters (Inches)

Figure 11. Tape dimensions

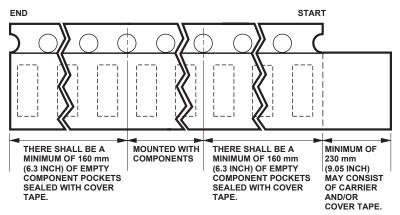


Figure 12. Tape leader and trailer dimensions

### **Reflow Soldering**

For more information on reflow soldering, refer to Application Note AN-1060, Surface Mounting SMT LED Indicator Components.

### **Storage Condition**

5 to 30°C @ 60%RH max.Baking is required before mounting, if

- 1. Humidity Indicator Card is > 10% when read at 23  $\pm$  5°C.
- 2. Device expose to factory conditions <30°C/60%RH more than 672 hours.

Recommended baking condition: 60±5°C for 20 hours.

